

**HAOPIN MICROELECTRONICS CO.,LTD.**

### Description

Passivated, sensitive gate triacs in a plastic envelope, intended for use in general purpose bidirectional switching and phase control applications, where high sensitivity is required in all four quadrants.

Symbol		Simplified outline
T2	T1	
Pin	Description	
1	Main terminal 1 (T1)	
2	Main terminal 2 (T2)	
3	gate (G)	
TAB	Main terminal 2 (T2)	

### Applications:

- ◆ Motor control
- ◆ Industrial and domestic lighting
- ◆ Heating
- ◆ Static switching

### Features

- ◆ Blocking voltage to 600 V
- ◆ On-state RMS current to 4 A

SYMBOL	PARAMETER	Value	Unit
$V_{DRM}$	Repetitive peak off-state voltages	600	V
$I_T$ (RMS)	RMS on-state current (full sine wave)	4	A
$I_{TSM}$	Non-repetitive peak on-state current	25	A

SYMBOL	PARAMETER	CONDITIONS	MIN	TYP	MAX	UNIT
$R_{thj-mb}$	Thermal resistance Junction to mounting base	Full cycle	-	-	3.0	K/W
		Half cycle	-	-	3.7	K/W
$R_{thj-a}$	Thermal resistance Junction to ambient	In free air	-	100	-	K/W



# BT134-600D

## Sensitive Gate Triacs

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Limiting values in accordance with the Maximum system(IEC 134)

SYMBOL	PARAMETER	CONDITIONS	MIN	Value	UNIT
$V_{DRM}$	Repetitive peak off-state Voltages		-	600	V
$I_{TRMS}$	RMS on-state current	Full sine wave; $T_{mb} \leq 107^\circ C$	-	4	A
$I_{TSM}$	Non-repetitive surge peak on-state current	full sine wave; $T_j = 25^\circ C$ prior to surge	t=20ms t=16.7ms	25 27	A
$I^2t$	$I^2t$ for fusing	$T=10ms$	-	3.1	$A^2s$
$dI_T/dt$	Repetitive rate of rise of on-state current after triggering	$I_{TM}=6A; I_G=0.2A;$ $dI_G/dt=0.2A/\mu s$	T2+G+	-	$A/\mu s$
			T2+G-	-	$A/\mu s$
			T2-G-	-	$A/\mu s$
			T2-G+	-	$A/\mu s$
			-	10	$A/\mu s$
$I_{GM}$	Peak gate current		-	2	A
$V_{GM}$	Peak gate voltage		-	5	V
$P_{GM}$	Peak gate power		-	5	W
$P_{G(AV)}$	Average gate power	Over any 20 ms period	-	0.5	W
$T_{stg}$	Storage temperature		-40	150	$^\circ C$
$T_j$	Operating junction Temperature		-	125	$^\circ C$

$T_j=25^\circ C$  unless otherwise stated

SYMBOL	PARAMETER	CONDITIONS	MIN	TYP	MAX	UNIT
Static characteristics						
$I_{GT1}$	Gate trigger current	$V_D=12V; I_T=0.1A$	T2+G+ T2+G- T2-G- T2-G+	- - - -	2.0 2.5 2.5 5.0	mA mA mA mA
$I_L$	Latching current	$V_D=12V; I_{GT}=0.1A$	T2+G+ T2+G- T2-G- T2-G+	- - - -	1.6 4.5 1.2 2.2	mA mA mA mA
$I_H$	Holding current	$V_D=12V; I_{GT}=0.1A$	-	1.2	10	mA
$V_T$	On-state voltage	$I_T=5A$	-	1.4	1.70	V
$V_{GT}$	Gate trigger voltage	$V_D=12V; I_T=0.1A$ $V_D=400V; I_T=0.1A; T_j=125^\circ C$	- 0.25	0.7 0.4	1.5 -	V V
$I_D$	Off-state leakage current	$V_D=V_{DRM(max)}; T_j=125^\circ C$	-	0.1	0.5	mA

### Dynamic Characteristics

$dV_D/dt$	Critical rate of rise of Off-state voltage	$V_{DM}=67\% V_{DRM(max)}; T_j=125^\circ C;$ Exponential wave form; $R_{GK}=1K\Omega$	-	5	-	$V/\mu s$
$t_{gt}$	Gate controlled turn-on time	$I_{TM}=6A; V_D=V_{DRM(max)}; I_G=0.1A;$ $dI_G/dt=5A/\mu s$	-	2	-	$\mu s$

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### Description

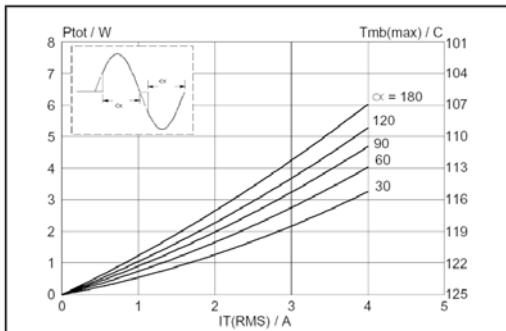


Fig.1. Maximum on-state dissipation,  $P_{tot}$ , versus rms on-state current,  $I_{T(RMS)}$ , where  $\alpha$  = conduction angle.

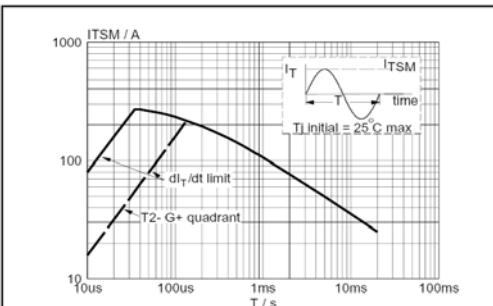


Fig.2. Maximum permissible non-repetitive peak on-state current  $I_{TSM}$ , versus pulse width  $t_p$ , for sinusoidal currents,  $t_p \leq 20\text{ms}$ .

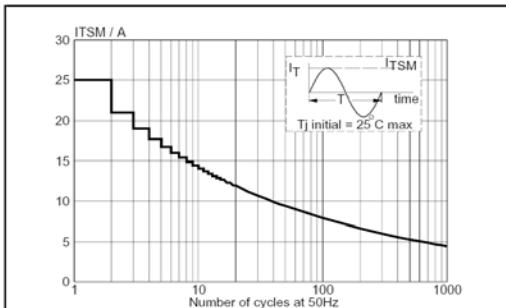


Fig.3. Maximum permissible non-repetitive peak on-state current  $I_{TSM}$ , versus number of cycles, for sinusoidal currents,  $f = 50\text{ Hz}$ .

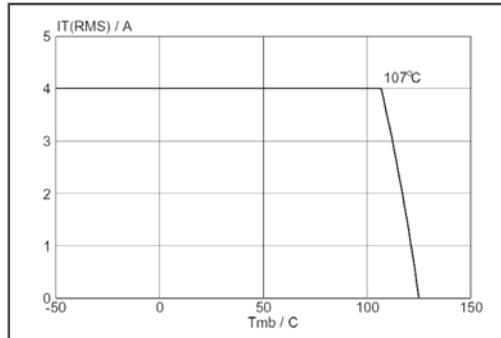


Fig.4. Maximum permissible rms current  $I_{T(RMS)}$ , versus mounting base temperature  $T_{mb}$ .

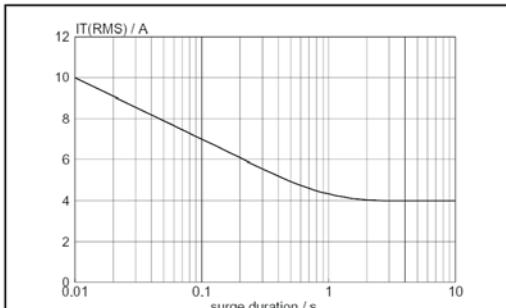


Fig.5. Maximum permissible repetitive rms on-state current  $I_{T(RMS)}$ , versus surge duration, for sinusoidal currents,  $f = 50\text{ Hz}$ ;  $T_{mb} \leq 107^\circ\text{C}$ .

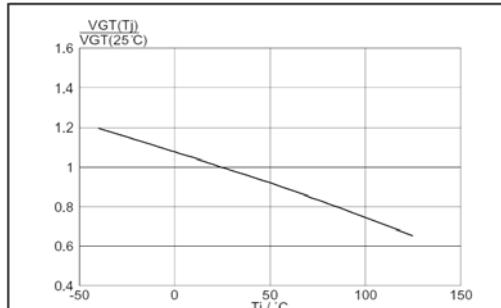


Fig.6. Normalised gate trigger voltage  $V_{GT}(T_j)/V_{GT}(25^\circ\text{C})$ , versus junction temperature  $T_j$ .

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### Description

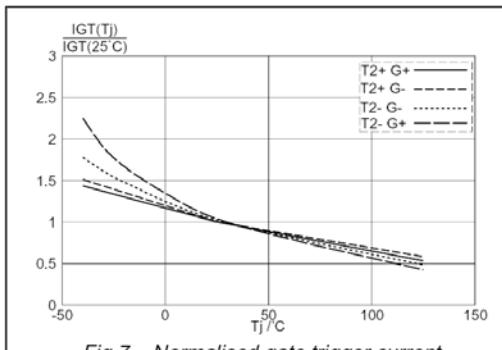


Fig.7. Normalised gate trigger current  $I_{GT}(T_j)/I_{GT}(25^\circ C)$ , versus junction temperature  $T_j$ .

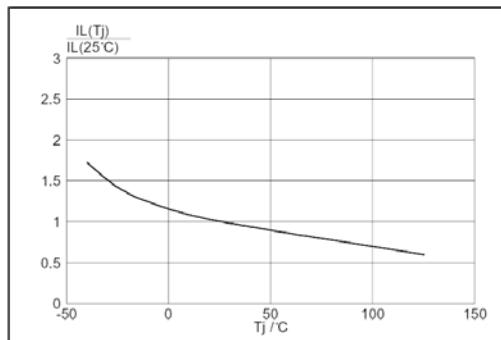


Fig.8. Normalised latching current  $I_L(T_j)/I_L(25^\circ C)$ , versus junction temperature  $T_j$ .

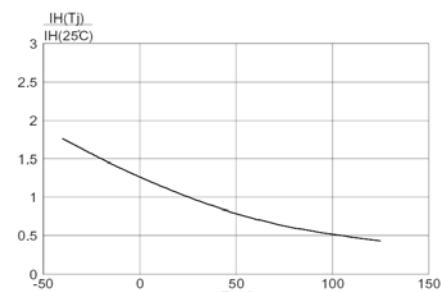


Fig.9. Normalised holding current  $I_h(T_j)/I_h(25^\circ C)$ , versus junction temperature  $T_j$ .

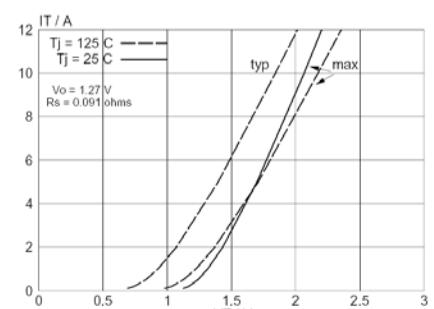


Fig.10. Typical and maximum on-state characteristic.

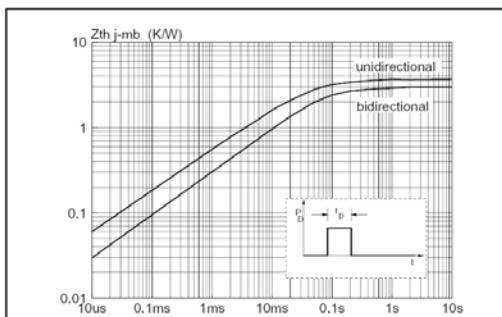


Fig.11. Transient thermal impedance  $Z_{th(j-mb)}$ , versus pulse width  $t_p$ .

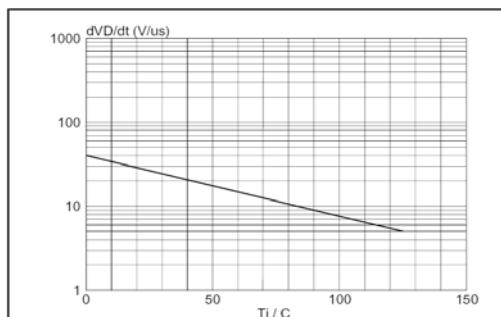


Fig.12. Typical, critical rate of rise of off-state voltage,  $dV_D/dt$  versus junction temperature  $T_j$ .

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## MECHANICAL DATA

Dimensions in mm

Net Mass: 0.8 g

SOT-82

